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PACKAGING DIVISION

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Best Paper of the Year Award
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PRESENTED TO

*Yasuo Takahashi, Hiroki Fukuda, Yasuhiro Yoneshima,
Hideki Kitamura, and Masakatsu Maeda*

*“EP-17-1026, Solid-State Microjoining Mechanisms of Wire
Bonding and Flip Chip Bonding”*

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